

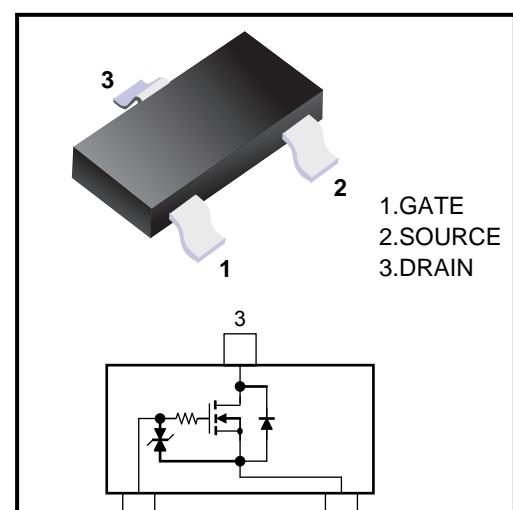
**60V N-Channel Enhancement MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	200mA
$V_{DSS}$	60V
$R_{DS(ON)-typ}(@V_{GS}=10V)$	<3.9Ω (Type: 2.8mΩ)
$R_{DS(ON)-typ}(@V_{GS}=5V)$	<8.1mΩ (Type: 5.4mΩ)
$R_{DS(ON)-typ}(@V_{GS}=4.5V)$	<4.7mΩ (Type: 3.2mΩ)

**High Speed Switching Applications**

♦ESD protected gate

Marking Code	
2N7002AK	NJ.


**Equivalent Circuit (top view)**
**SOT23-3L**
**Absolute Maximum Ratings Ta = 25°C**

Characteristic	Symbol	Rating	Unit
Drain- source voltage	$V_{DSS}$	60	V
Gate-source voltage	$V_{GSS}$	± 20	V
Drain current (Note1)	DC	$I_D$	200
	Pulse	$I_{DP}$	760
Power dissipation (Note 3) (Note 4)	$P_D$	320	mW
	$P_D$	1000	
Channel temperature	$T_{ch}$	150	°C
Storage temperature	$T_{stg}$	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Note 1: The channel temperature should not exceed 150°C during use.

Note 2: Pulse width ≤ 10 μs, Duty ≤ 1%

Note 3: Mounted on an FR4 board

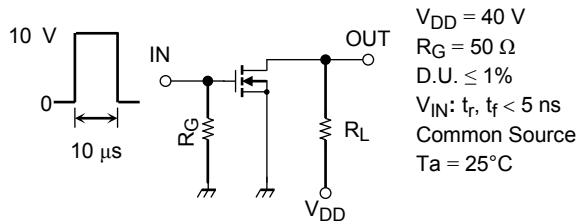
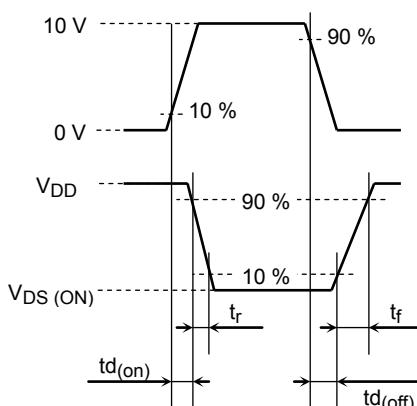
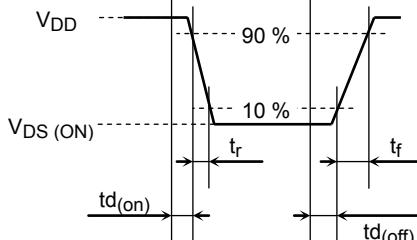
(25.4 mm · 25.4 mm · 1.6 mm, Cu Pad: 0.42 mm² x 3)

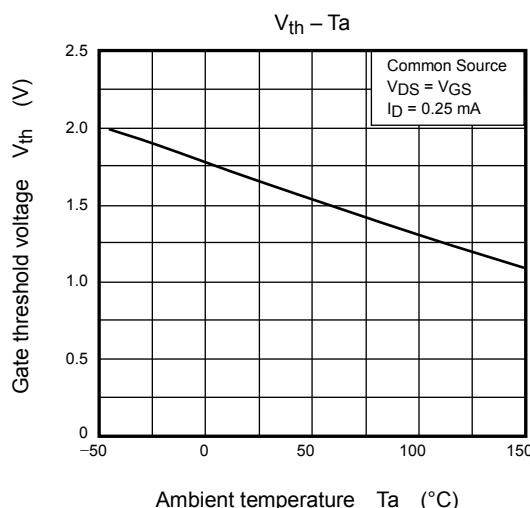
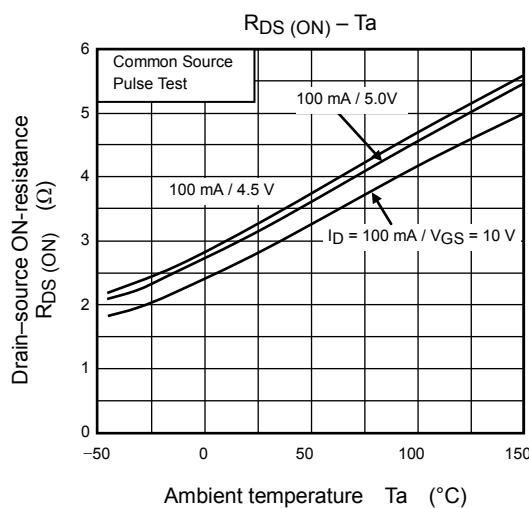
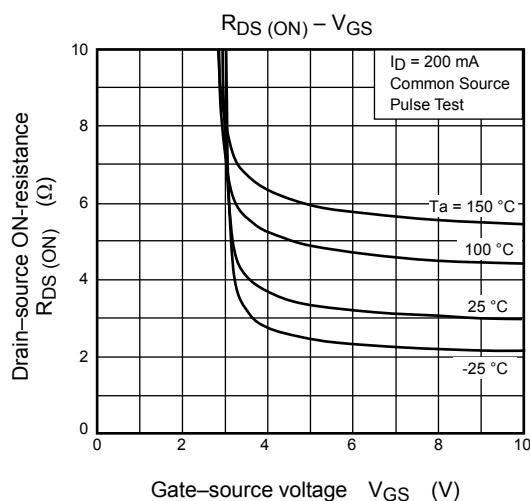
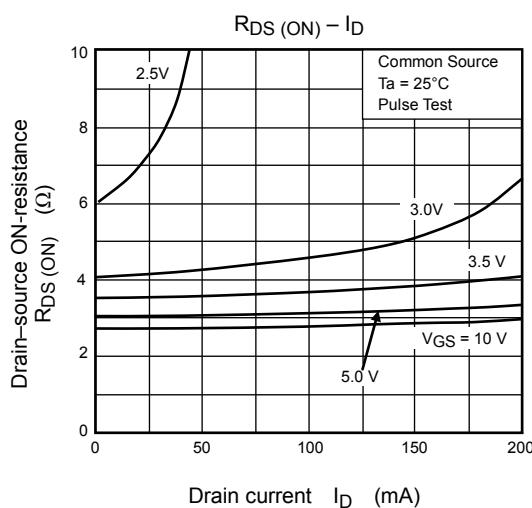
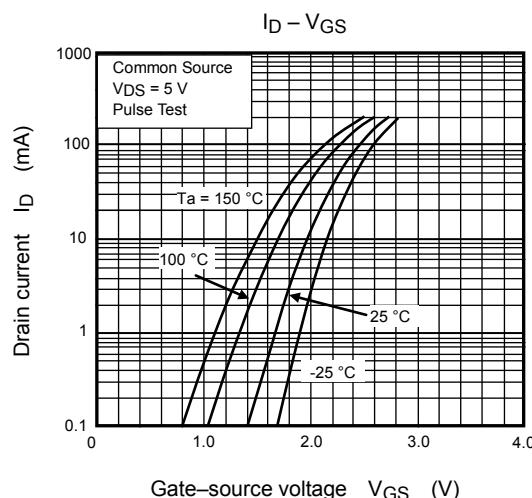
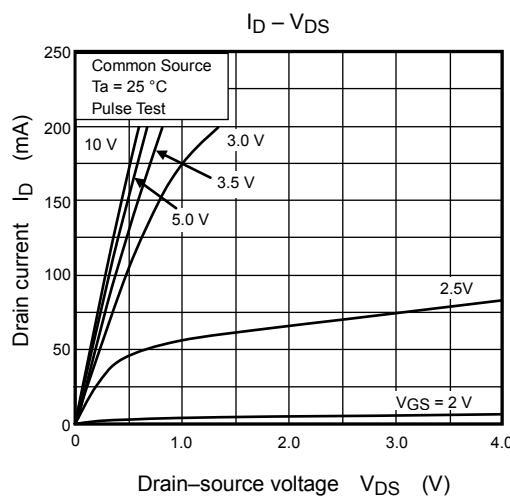
Note 4: Mounted on an FR4 board

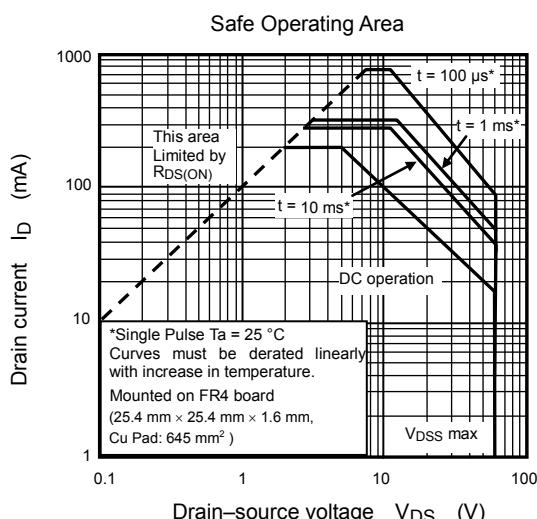
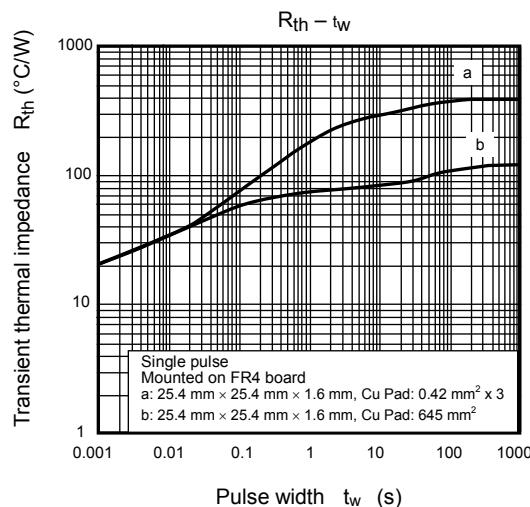
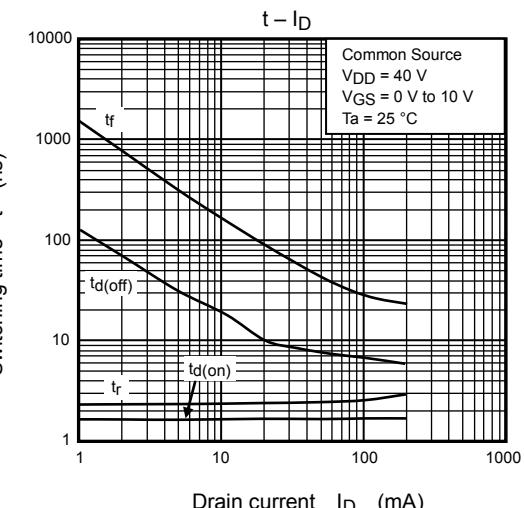
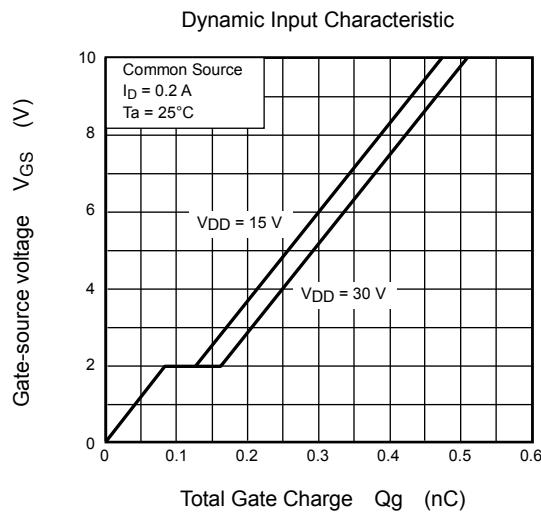
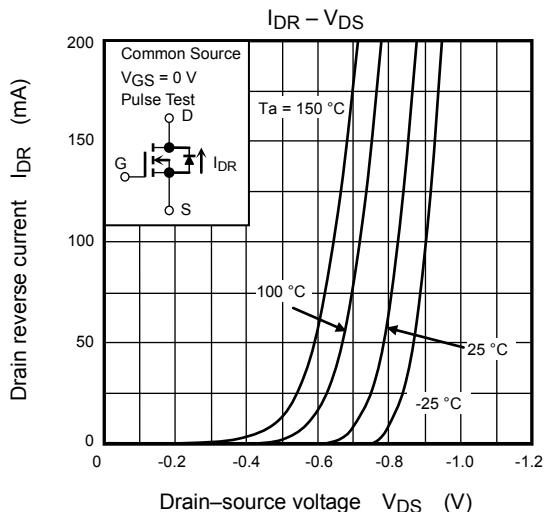
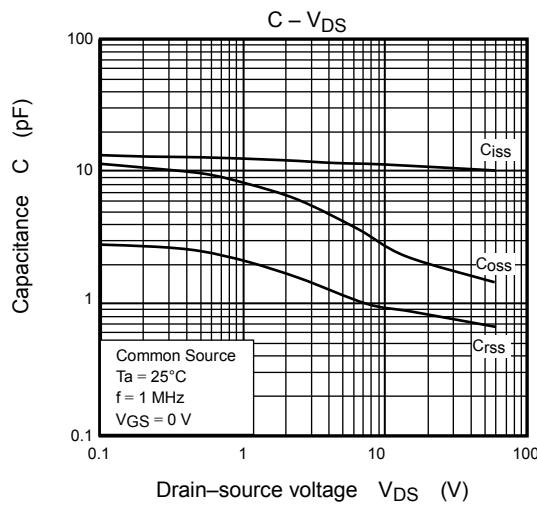
(25.4 mm · 25.4 mm · 1.6 mm, Cu Pad: 645 mm² )

**Electrical Characteristics Ta = 25°C**

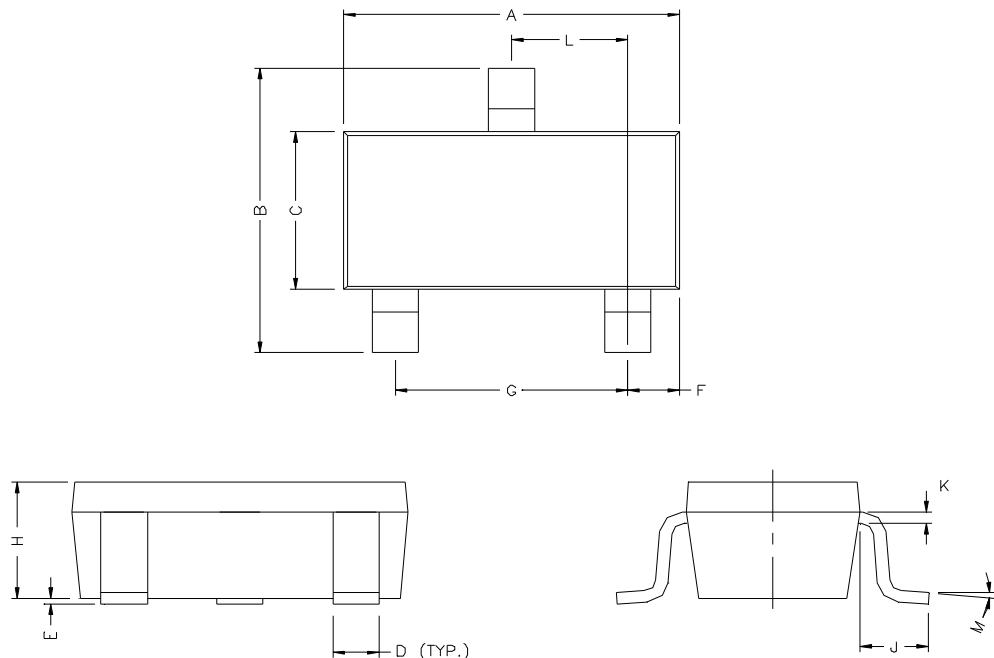
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 250\mu A, V_{GS} = 0 V$	60	—	—	V
Drain cutoff current	$I_{DSS}$	$V_{DS} = 60 V, V_{GS} = 0 V$	—	—	1	$\mu A$
		$V_{DS} = 60 V, V_{GS} = 0 V, T_j=150 ^\circ C$	—	—	200	
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 16 V, V_{DS} = 0 V$	—	—	$\pm 2$	$\mu A$
		$V_{GS} = \pm 10 V, V_{DS} = 0 V$	—	—	$\pm 0.5$	
		$V_{GS} = \pm 5 V, V_{DS} = 0 V$	—	—	$\pm 0.1$	
Gate threshold voltage	$V_{th}$	$I_D = 250 \mu A, V_{DS} = V_{GS}$	1.1	—	2.1	V
Forward transfer admittance (Note 5)	$ Y_{fs} $	$V_{DS} = 10 V, I_D = 200 mA$	—	450	—	mS
Drain-source ON-resistance (Note 5)	$R_{DS(ON)}$	$I_D = 100 mA, V_{GS} = 10 V$	—	2.8	3.9	$\Omega$
		$I_D = 100 mA, V_{GS} = 10 V, T_j=150 ^\circ C$	—	5.4	8.1	
		$I_D = 100 mA, V_{GS}= 5 V$	—	3.1	4.4	
		$I_D = 100 mA, V_{GS} = 4.5 V$	—	3.2	4.7	
Total Gate Charge	$Q_{G(tot)}$	$V_{DS} = 30 V, I_D = 200mA$ $V_{GS}= 4.5 V$	—	0.27	0.35	nC
Gate-Source Charge	$Q_{GS}$		—	0.08	—	
Gate-Drain Charge	$Q_{GD}$		—	0.08	—	
Input capacitance	$C_{iss}$	$V_{DS} = 10 V, V_{GS}= 0 V, f = 1 MHz$	—	11	17	pF
Output capacitance	$C_{oss}$		—	3	—	
Reverse transfer capacitance	$C_{rss}$		—	0.7	—	
Switching time	Turn-on delay time	$t_{d(on)}$	—	2	4	ns
	Rise time	$t_r$	—	3	—	
	Turn-off delay time	$t_{d(off)}$	—	7	14	
	Fall time	$t_f$	—	24	—	
Drain-source forward voltage (Note 5)	$V_{DSF}$	$I_D = -115 mA, V_{gs} = 0 V$	—	-0.87	-1.2	V

**Switching Time Test Circuit**
**(a) Test Circuit**

**(b)  $V_{IN}$** 

**(c)  $V_{OUT}$** 






Note: The above characteristics curves are presented for reference only and not guaranteed by production test.

**Package Outline**
**SOT23-3L**

**DIMENSIONS (mm are the original dimensions)**

UNIT	A	B	C	D	E	F	G	H	K	J	L	M
mm	2.70 3.10	2.65 2.95	1.50 1.70	0.35 0.50	0 0.10	0.45 0.55	1.9	1.00 1.30	0.10 0.20	0.40 -	0.85 1.15	0° 10°

**Summary of Packing Options**

Package	Package Description	Packing Quantity	Industry Standard
SOT23-3L	Tape/Reel,7"reel	3000	EIA-481-1